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(12) **United States Design Patent**
Wong

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(54) **ELECTRONIC MODULE**

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(**) Term: **14 Years**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/162**

(58) **Field of Classification Search** D13/110, D13/123, 162, 162.1; D14/439; 361/679.02, 361/690, 728, 729, 730, 796; 700/1, 17, 700/18, 20; 439/709, 715, 716
See application file for complete search history.

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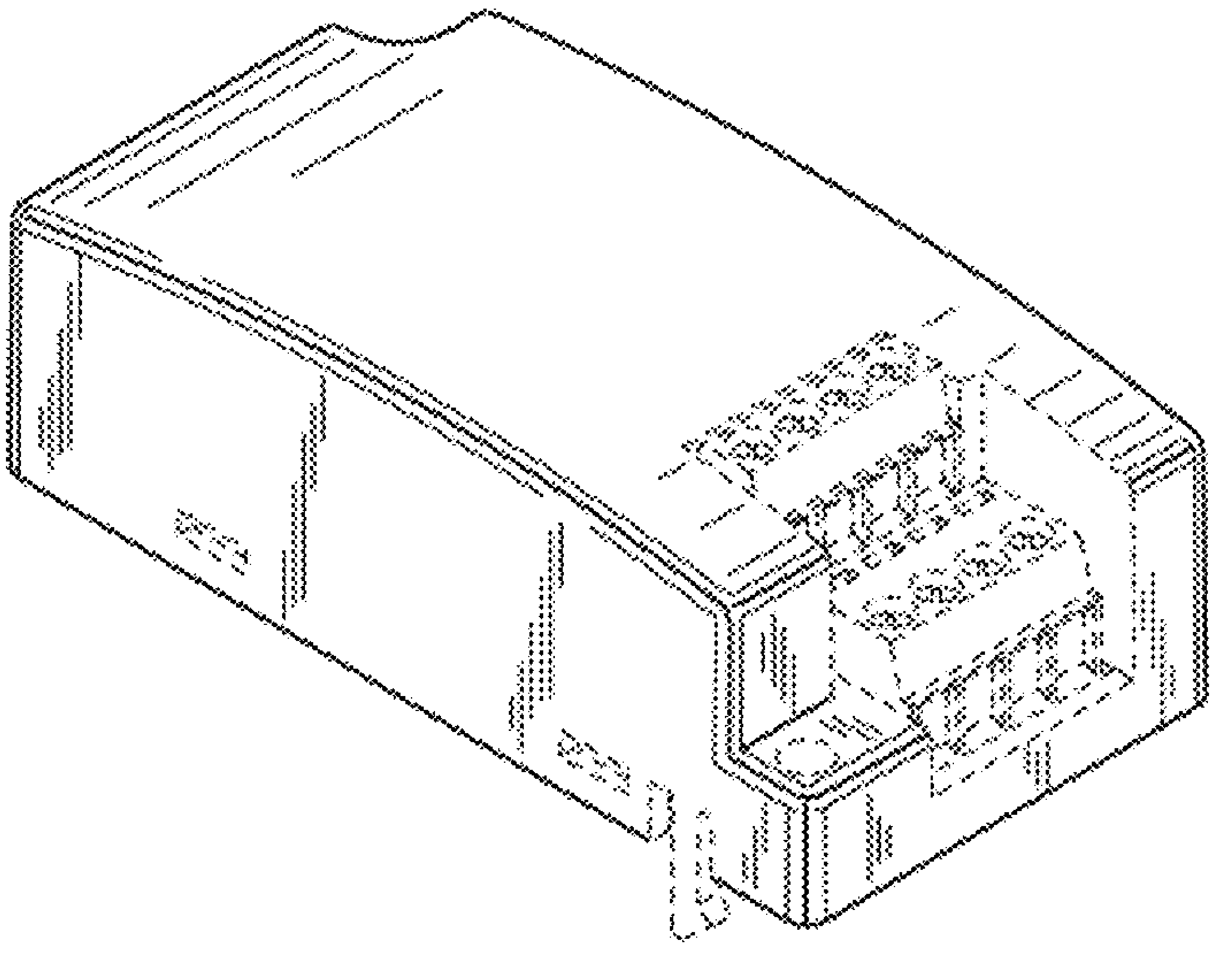
(57) **CLAIM**

The ornamental design for an electronic module, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of the design for the electronic module, wherein connection features that facilitate access to internal components of the electronic module and enable attachment of the electronic module to separate devices are shown in broken lines for illustrative purposes;
FIG. **2** is a front elevational view of the electronic module set forth in FIG. **1**;
FIG. **3** is top plan view of the electronic module set forth in FIG. **1**;
FIG. **4** is a right side elevational view of the electronic module set forth in FIG. **1**;
FIG. **5** is a left side elevational view of the electronic module set forth in FIG. **1**;
FIG. **6** is a rear elevational view of the electronic module set forth in FIG. **1**; and,
FIG. **7** is a bottom plan view of the electronic module set forth in FIG. **1**.
In these drawings, the solid lines illustrate the claimed ornamental design, whereas the broken lines illustrate environmental features that form no part of the claimed ornamental design.

1 Claim, 4 Drawing Sheets



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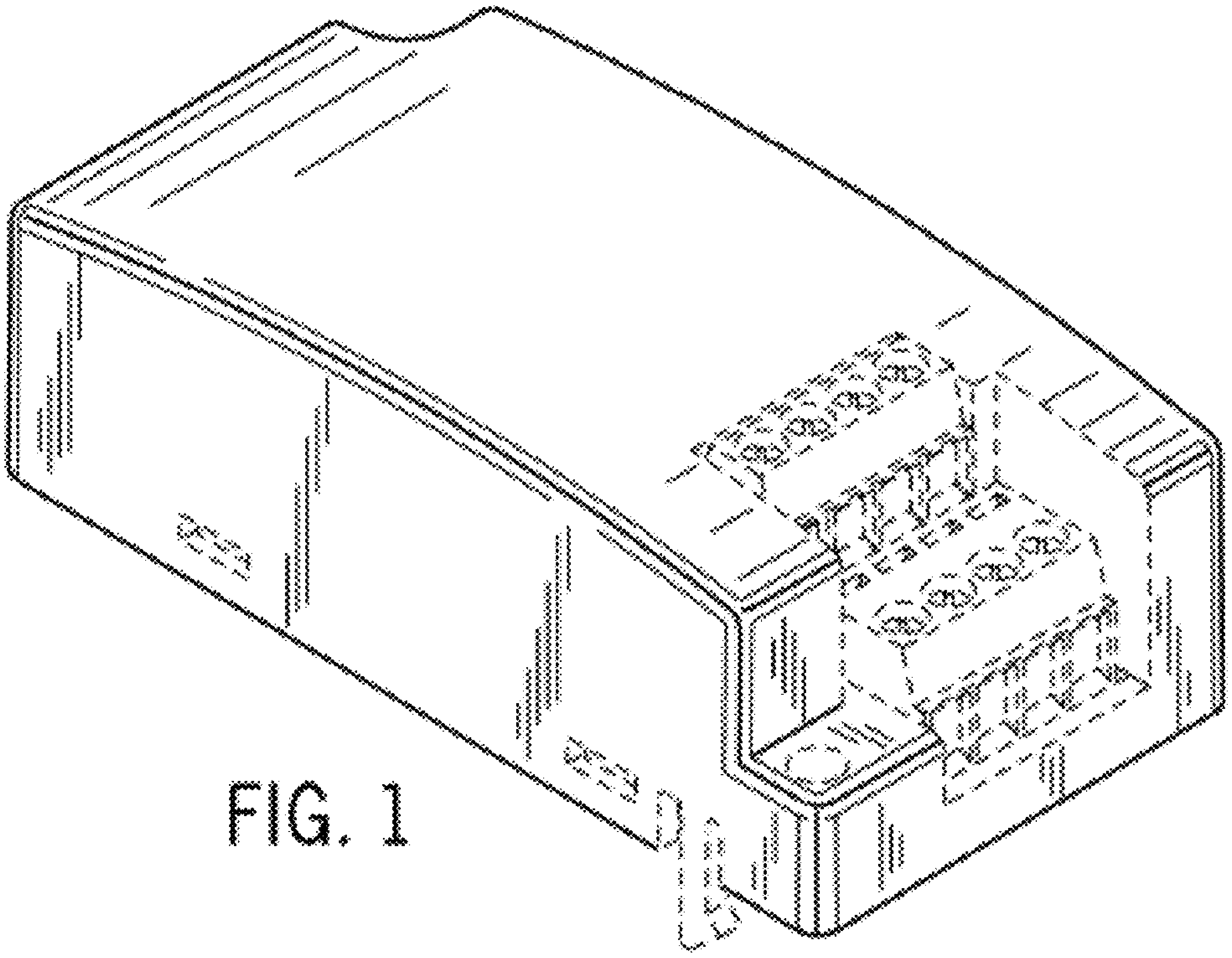


FIG. 1

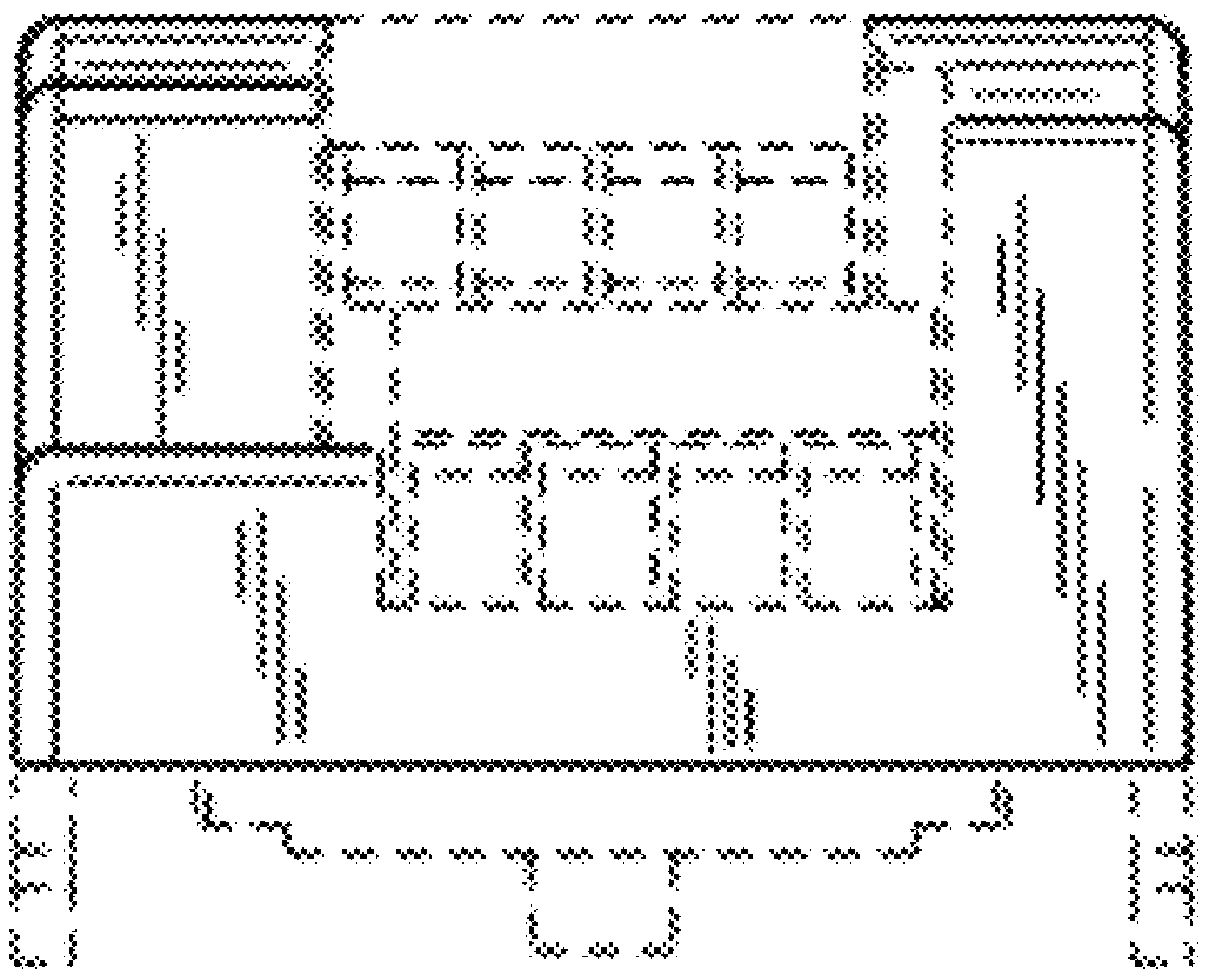
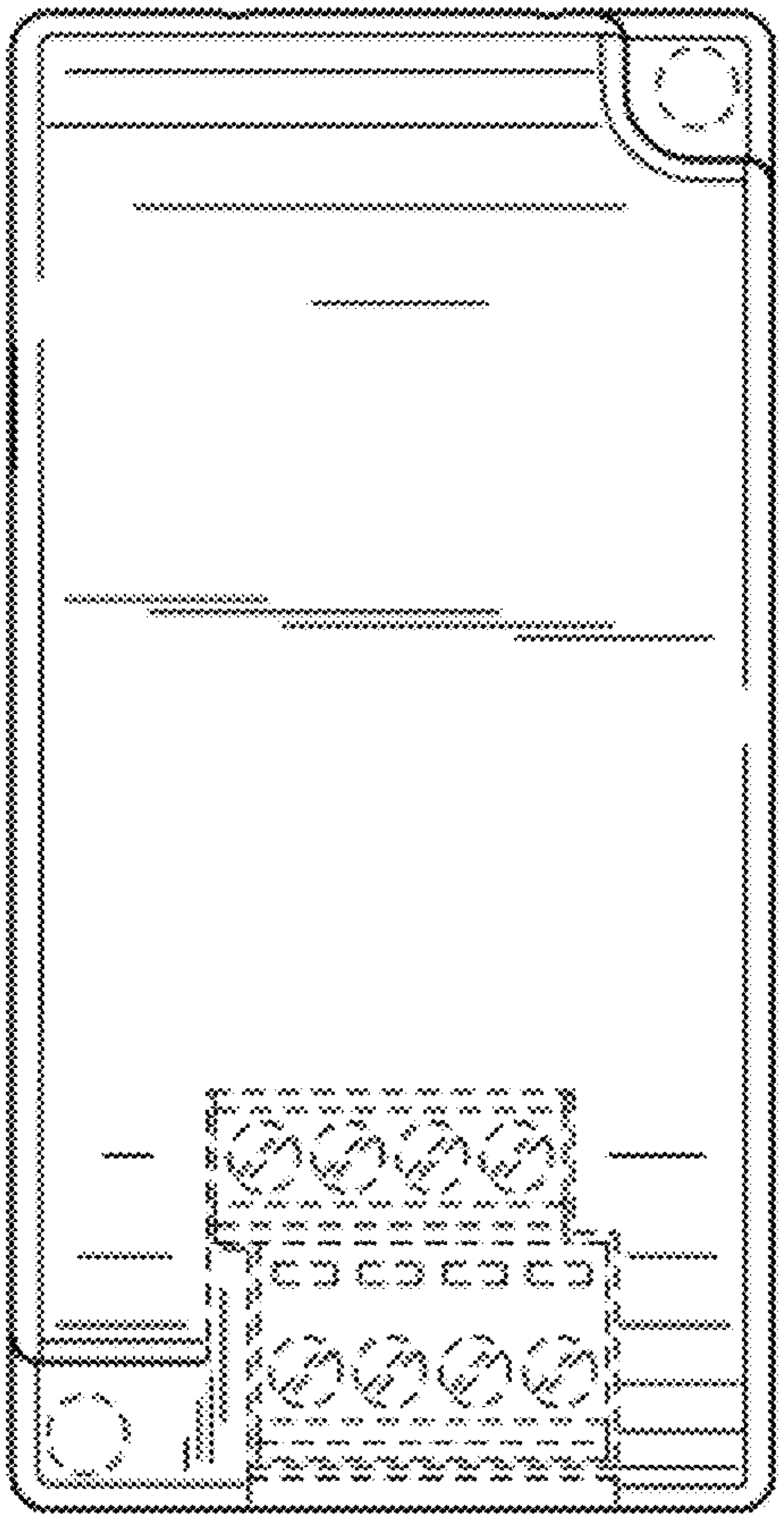


FIG. 2

FIG. 3



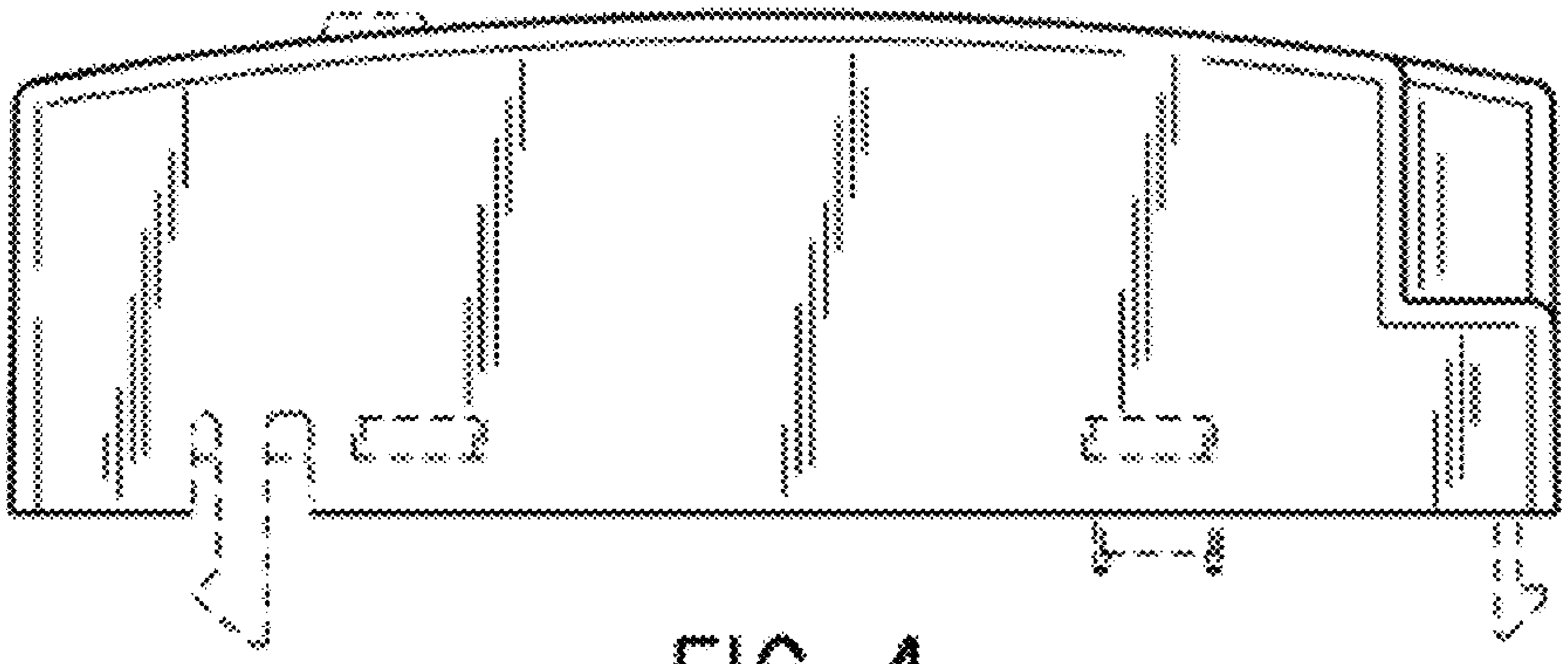


FIG. 4

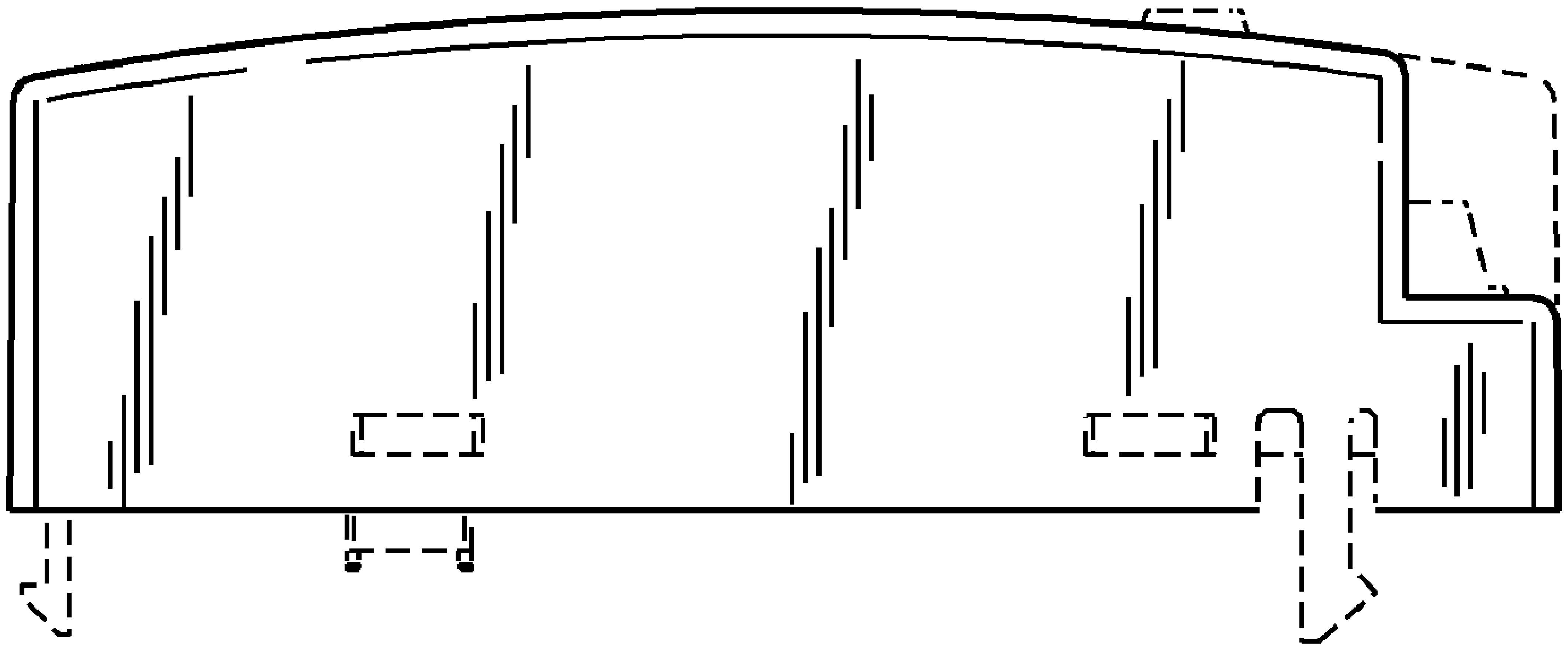


FIG. 5

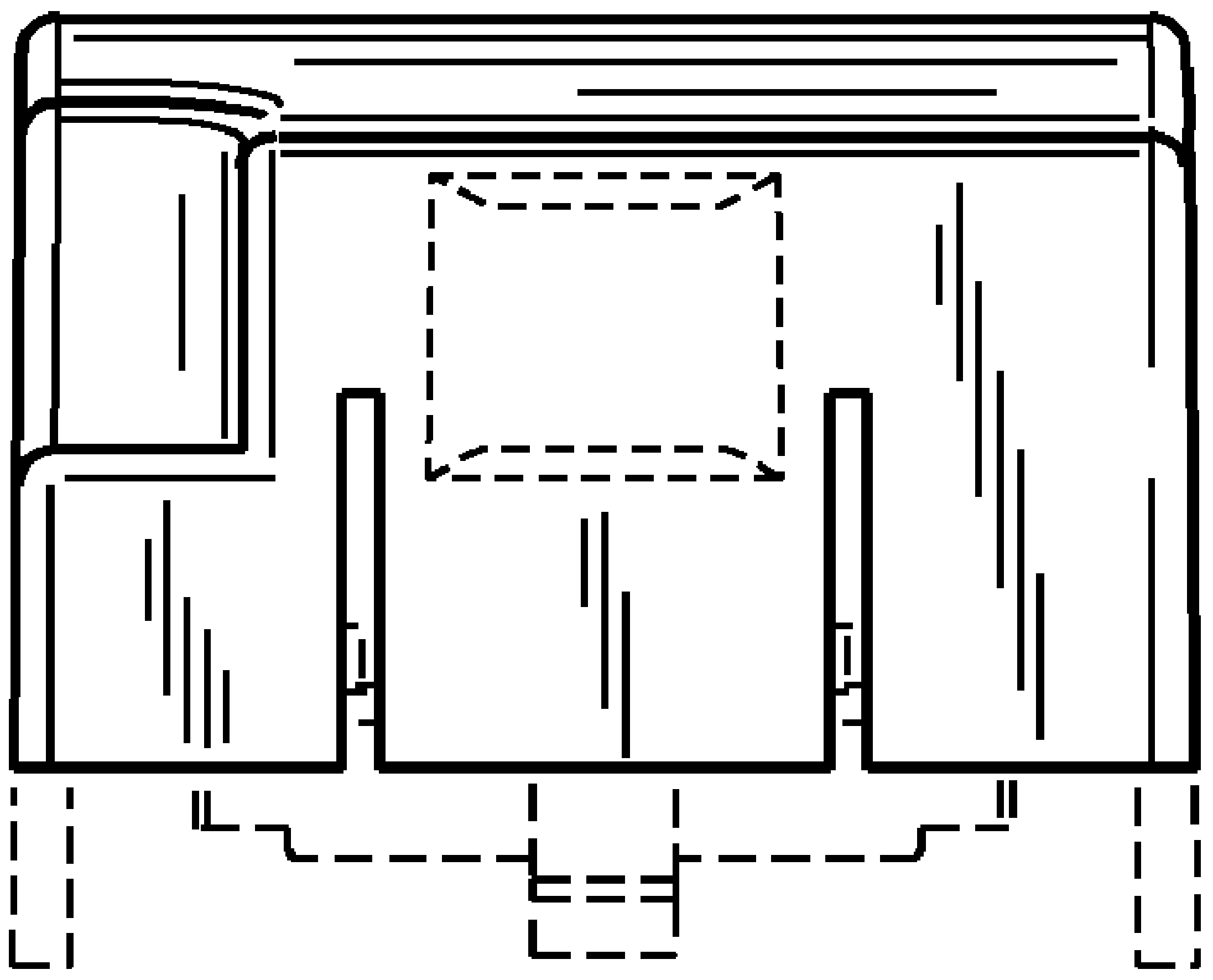


FIG. 6

FIG. 7